

ABSTRACT

A shielded multi-conductor interconnect bus for use in interconnecting MEM devices with control signal sources or the like and a method of fabricating a shielded multi-conductor interconnect bus are disclosed. In one embodiment, a shielded interconnect bus formed on a substrate (20) includes a plurality of electrically conductive lines (42) arranged in sets of one, two or more conductive lines between electrically conductive shield walls (46, 66). The electrically conductive lines (42) are surrounded by layers of dielectric material (30, 50). An electrically conductive shield (78) overlies the electrically conductive lines (42) and electrically conductive shield walls (46, 66).

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